

2SC5244, 2SC5244A

Silicon NPN triple diffusion mesa type

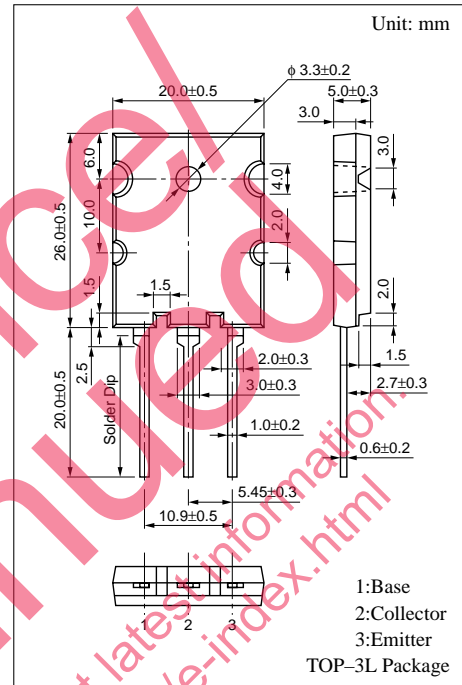
For horizontal deflection output

■ Features

- High breakdown voltage, and high reliability through the use of a glass passivation layer
- High-speed switching
- Wide area of safe operation (ASO)

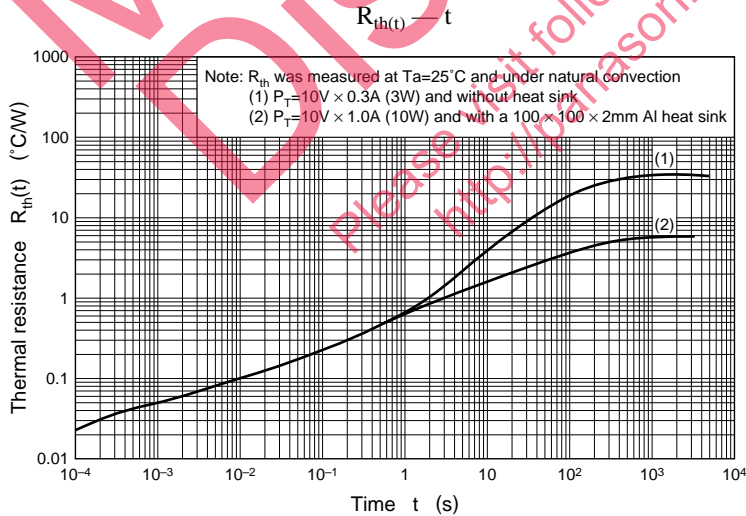
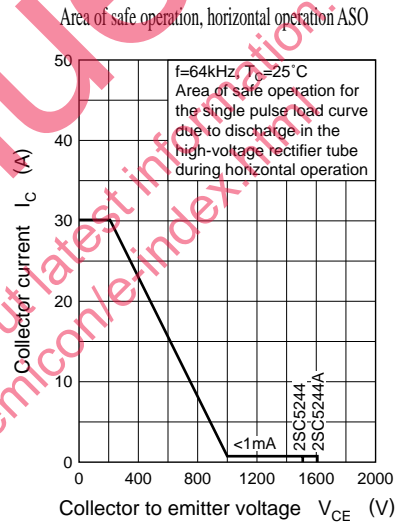
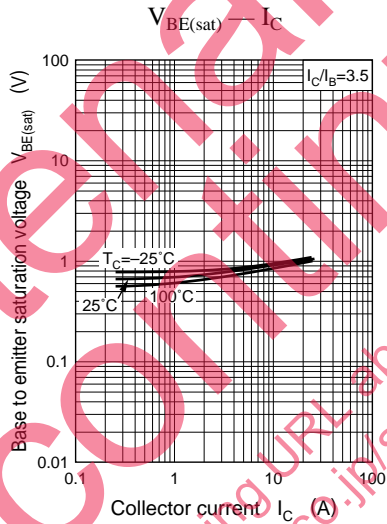
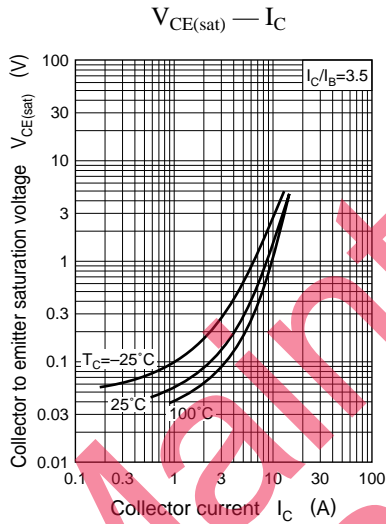
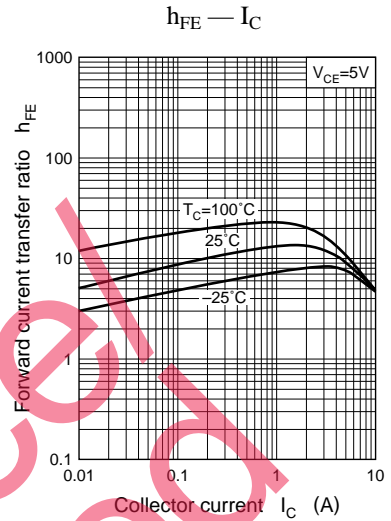
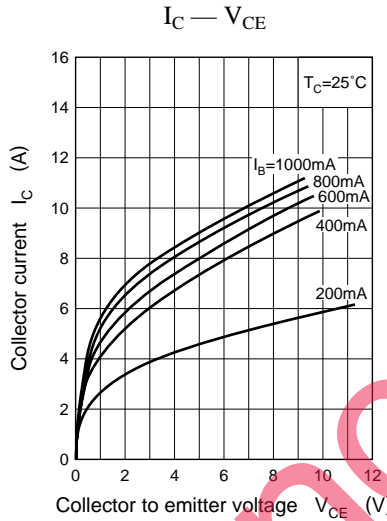
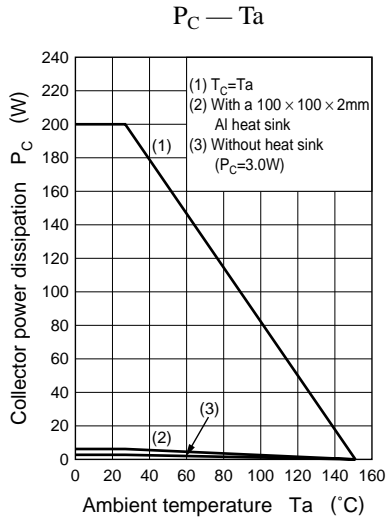
■ Absolute Maximum Ratings (T_C=25°C)

Parameter	Symbol	Ratings	Unit	
Collector to base voltage	V _{CBO}	1500	V	
2SC5244A		1600		
Collector to emitter voltage	V _{CES}	1500	V	
2SC5244A		1600		
Emitter to base voltage	V _{EBO}	6	V	
Peak collector current	I _{CP}	20	A	
Collector current	I _C	30	A	
Collector power dissipation	P _C	T _C =25°C	200	W
		T _a =25°C	3.5	
Junction temperature	T _j	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	



■ Electrical Characteristics (T_C=25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I _{CBO}	V _{CB} = 1500V, I _E = 0			1	mA
		V _{CB} = 1600V, I _E = 0			1	
Emitter cutoff current	I _{EBO}	V _{EB} = 5V, I _C = 0			50	μA
Forward current transfer ratio	h _{FE}	V _{CE} = 5V, I _C = 10A	5		12	
Collector to emitter saturation voltage	V _{CE(sat)}	I _C = 10A, I _B = 2.8A			3	V
Base to emitter saturation voltage	V _{BE(sat)}	I _C = 10A, I _B = 2.8A			1.5	V
Transition frequency	f _T	V _{CE} = 10V, I _C = 0.1A, f = 0.5MHz		3		MHz
Storage time	t _{stg}	I _C = 12A, I _{B1} = 2.4A, I _{B2} = -4.8A, Resistance loaded		1.5	2.5	μs
Fall time	t _f			0.12	0.2	μs



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